

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claims 1-2 (canceled)

Claim 3 (currently amended) A planarizing support layer provided on a bumped surface

of one of a bumped-die and or a bumped wafer, the support layer comprising a pre-back-grind under-fill layer both to provide substantially planar back-grind wafer support during any back-grind process, and to provide under-fill material during any mounting/under-fill process, the under-fill layer covering at least a substantial majority of bump-bodies of bumps on the bumped surface, while leaving a remainder portion of the bump bodies exposed; and

an adhesive protection tape including a flexible conforming layer applied to the under-fill layer, the conforming layer to cover the remainder portion of the bump-bodies not covered by the under-fill layer, to further improve a planarity of the support layer

Claim 4 (currently amended) A planarizing support layer provided on a bumped surface

of one of a bumped-die and or a bumped-wafer, the support layer comprising a pre-back-grind under-fill layer both to provide substantially planar back-grind wafer support during any back-grind process, and to provide under-fill material during any mounting/under-fill process, the under-fill layer covering an entirety of bump-bodies of bumps on the bumped surface.

Claim 5 (original) A support layer as claimed in claim 4, the support layer further comprising an adhesive protection tape applied to the under-fill layer.

Claim 6 (previously presented) A support layer as claimed in claim 4, the under-fill layer being of a thickness beyond a height thickness of the bump-bodies, to provide additional under-fill material to under-fill structures other than the bumps during any mounting/under-fill process.

Claim 7 (previously presented) A support layer as claimed in claim 4, the under-fill layer comprising a polymer material.

Claim 8 (currently amended) A support layer as claimed in claim 4, the under-fill layer comprising one of a thermoplastic ~~and~~ or a thermoset polymer material.

Claim 9 (currently amended) A support layer as claimed in claim 4, the under-fill layer comprising one of a thermoplastic material, thermoset material, light-curable material ~~and~~ or a chemical-curable material.

Claim 10 (currently amended) A support layer as claimed in claim 4, the under-fill layer comprising an opaque material to provide at least one of light, ultra-violet (UV) light, ~~and~~ or radiation protection to a surface of the bumped-die or bumped-wafer.

Claims 11-12 (canceled)

Claim 13 (currently amended) A back-grind/mounting arrangement comprising one of a bumped-die ~~and~~ or a bumped wafer comprising: a planarizing support layer provided on a bumped surface of the bumped-die or bumped-wafer, the support layer comprising a pre-back-grind under-fill layer both to provide substantially planar back-grind wafer support during any back-grind process, and to provide under-fill material during any mounting/under-fill process, the under-fill layer

covering at least a substantial majority of bump-bodies of bumps on the bumped surface, while leaving a remainder portion of the bump-bodies exposed; and

an adhesive protection tape including a flexible conforming layer applied to the under-fill layer, the conforming layer to cover the remainder portion of the bump-bodies not covered by the under-fill layer, to further improve a planarity of the support layer.

Claim 14 (currently amended) An arrangement as claimed in claim 13, the arrangement further comprising a secondary under-fill layer disposed on a bonding substrate to under-fill at least one of: the remainder portion of the bump-bodies not covered by the under-fill layer, ~~and~~ or structures other than the bumps as encountered during any mounting process.

Claim 15 (currently amended) A back-grind/mounting arrangement comprising one of a bumped-die ~~and~~ or a bumped wafer comprising: a planarizing support layer provided on a bumped surface of the bumped-die or bumped-wafer, the support layer comprising a pre-back-grind under-fill layer both to provide substantially planar back-grind wafer support during any back-grind process, and to provide under-fill material during any mounting/under-fill process, the under-fill layer covering an entirety of bump-bodies bumps on the bumped surface.

Claim 16 (original) An arrangement as claimed in claim 15, the support layer further comprising an adhesive protection tape applied to the under-fill layer.

Claim 17 (previously presented) An arrangement as claimed in claim 15, the under-fill layer being of a thickness beyond a height thickness of the bump-bodies, to

provide additional under-fill material to under-fill structures other than the bumps as encountered during any mounting process.

Claim 18 (previously presented) An arrangement as claimed in claim 15, the under-fill layer comprising a polymer material.

Claim 19 (currently amended) An arrangement as claimed in claim 15, the under-fill layer comprising one of a thermoplastic ~~and~~ or a thermoset polymer material.

Claim 20 (currently amended) An arrangement as claimed in claim 15, the under-fill layer comprising one of a thermoplastic material, thermoset material, light-curable material ~~and~~ or a chemical-curable material.

Claim 21 (currently amended) An arrangement as claimed in claim 15, the under-fill layer comprising an opaque material to provide at least one of light, ultra-violet (UV) light, ~~and~~ or radiation protection to a surface of the bumped-die or bumped wafer.

Claim 22 (previously presented) An arrangement as claimed in claim 15, wherein the arrangement is a flip-chip back-grind/mounting arrangement.

Claims 23-24 (canceled)

Claim 25 (currently amended) A back-grind/mounting method useable with either one of a bumped-die ~~and~~ or a bumped wafer, the method comprising: providing a planarizing support layer on a bumped surface of the bumped-die or bumped-wafer, the support layer comprising a pre-back-grind under-fill layer both to provide substantially planar back-grind wafer support during any back-grind process, and to provide under-fill material during any mounting/under-fill process, the under-fill layer covering at least a substantial majority of bump-bodies of

bumps on the bumped surface, while leaving a remainder portion of the bump-bodies exposed; and

an adhesive protection tape including a flexible conforming layer applied to the under-fill layer, the conforming layer to cover the remainder portion of the bump-bodies not covered by the under-fill layer, to further improve planarity of the support layer.

Claim 26 (currently amended) A method as claimed in claim 25, the method further comprising: providing a secondary under-fill layer disposed on a bonding substrate to under-fill at least one of: the remainder portion of the bump-bodies not covered by the under-fill layer, ~~and~~ or structures other than the bumps encountered during any mounting process.

Claim 27 (currently amended) A back-grind/mounting method useable with either one of a bumped-die ~~and~~ or a bumped wafer, the method comprising: providing a planarizing layer comprising a pre-back-grind under-fill layer both to provide substantially planar back-grind wafer support during any back-grind process, and to provide under-fill support layer on a bumped surface of the bumped-die or bumped-wafer, the support material during any mounting/under-fill process, the under-fill layer covering an entirety of bump-bodies of bumps on the bumped surface.

Claim 28 (original) A method as claimed in claim 27, the support layer further comprising an adhesive protection tape applied to the under-fill layer.

Claim 29 (previously presented) A method as claimed in claim 27, the under-fill layer being of a thickness beyond a height thickness of the bump-bodies, to provide

additional under-fill material to under-fill structures other than the bumps as encountered during any mounting process.

Claim 30 (previously presented) A method as claimed in claim 27, the under-fill layer comprising a polymer material.

Claim 31 (currently amended) A method as claimed in claim 27, the under-fill layer comprising one of a thermoplastic ~~and~~ or a thermoset polymer material.

Claim 32 (currently amended) A method as claimed in claim 27, the under-fill layer comprising one of a thermoplastic material, thermoset material, light-curable material ~~and~~ or a chemical-curable material

Claim 33 (currently amended) A method as claimed in claim 27, the under-fill layer comprising an opaque material to provide at least one of light, ultra-violet (UV) light, ~~and~~ or radiation protection to a surface of the bumped-die or bumped wafer.

Claim 34 (previously presented) A method as claimed in claim 27, wherein the method is a flip-chip back-grind/mounting method.